

**Neifeld Docket No:** OSEMDB30UPCTUS

Application/Patent No: 10/581,316

USPTO CONFIRMATION NO: 3859

File/Issue Date: 10/581,316

Inventor/Title: Braddock/High Temperature Vacuum Evaporation Apparatus

Examiner/ArtUnit: /1792

**37 CFR 1.7(c) FILING RECEIPT AND TRANSMITTAL LETTER WITH  
AUTHORIZATION TO CHARGE DEPOSIT ACCOUNT**

1. **THE COMMISSIONER IS HEREBY AUTHORIZED TO CHARGE ANY FEES  
WHICH MAY BE REQUIRED, OR CREDIT ANY OVERPAYMENT, TO DEPOSIT  
ACCOUNT NUMBER 50-2106.**

2. **FEES (PAID HERewith BY EFS CREDIT CARD SUBMISSION) \$:**

A. **CLAIMS FEES**

\$ - ( claims previously paid for; currently present; \$52 per addl. claim over 20.)

\$ - ( independent previously paid for; currently present; \$220 per addl. claim over 3)

B. **OTHER FEES**

\$ (Fee for filing a \_\_\_\_\_)

3. **THE FOLLOWING DOCUMENTS ARE SUBMITTED HERewith:**

37 CFR 1.115 SECOND PRELIMINARY AMENDMENT (5 pages)

4. **FOR INTERNAL NEIFELD IP LAW, PC USE ONLY**

USPTO CHARGES \$: CLIENT BILLING MATTER: BANK ACCOUNT/Check: 6/ G/L ACCOUNT: 5010	FIRM CHARGES \$: DESCRIPTION: FIRM CHARGE FOR LAWYER:
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INITIALS OF PERSON WHO **ENTERED** ACCOUNTING DATA:

ATTORNEY SIGNATURE (AUTHORIZING DEPOSIT ACCOUNT)

**DATE:** 11/21/2008

**SIGNATURE:** /Bruce Margulies/

Printed: November 24, 2008 (2:48pm)

Bruce Margulies

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NEIFELD DOCKET NO: OSEMDB30UPCTUS

IN THE UNITED STATES PATENT & TRADEMARK OFFICE

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ASSISTANT COMMISSIONER FOR PATENTS

ALEXANDRIA, VA 22313

37 CFR 1.115 SECOND PRELIMINARY AMENDMENT

Sir:

In response to the notice of non-compliant amendment mailed November 14, 2008, the applicant submits this response.